**Product data sheet** 



### 1.1 General description

Planar PIN diode in a SOD882 leadless ultra small SMD plastic package.

#### 1.2 Features

- High speed switching for RF signals
- Low diode capacitance
- Low forward resistance
- Very low series inductance
- For applications up to 3 GHz

### 1.3 Applications

RF attenuators and switches

### 2. Pinning information

Table 1:	Pinning		
Pin	Description	Simplified outline	Symbol
1	cathode	<u>[1]</u>	14
2	anode	1 2	sym006
		Transparent top view	

<sup>[1]</sup> The marking bar indicates the cathode

## 3. Ordering information

**Table 2: Ordering information** 

Type number	Package			
	Name	Description	Version	
BAP51L	-	leadless ultra small plastic package; 2 terminals; body $1.0 \times 0.6 \times 0.5$ mm	SOD882	





Table 3: Marking

Type number	Marking code
BAP51L	E2

## 5. Limiting values

Table 4: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_R$	reverse voltage		-	60	V
I <sub>F</sub>	forward current		-	100	mA
P <sub>tot</sub>	total power dissipation	T <sub>sp</sub> = 90 °C	-	500	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-65	+150	°C

### 6. Thermal characteristics

Table 5: Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		100	K/W

### 7. Characteristics

Table 6: Electrical characteristics

 $T_i = 25 \,^{\circ}C$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{F}$	forward voltage	I <sub>F</sub> = 50 mA	-	0.95	1.1	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 50 V	-	-	100	nA
C <sub>d</sub>	diode capacitance	f = 1 MHz; see Figure 2				
		$V_R = 0 V$	-	0.30	-	pF
		V <sub>R</sub> = 1 V	-	0.23	0.4	pF
		V <sub>R</sub> = 5 V	-	0.17	0.3	pF
r <sub>D</sub>	diode forward resistance	f = 100 MHz; see Figure 1				
		$I_F = 0.5 \text{ mA}$	-	5.3	9	Ω
		I <sub>F</sub> = 1 mA	-	3.5	6.5	Ω
		I <sub>F</sub> = 10 mA	-	1.4	2.5	Ω
		I <sub>F</sub> = 100 mA	-	0.9	1.5	Ω
s <sub>21</sub>   <sup>2</sup>	isolation	V <sub>R</sub> = 0 V; see Figure 4				
		f = 900 MHz	-	19	-	dB
		f = 1800 MHz	-	15	-	dB
		f = 2450 MHz	-	13	-	dB

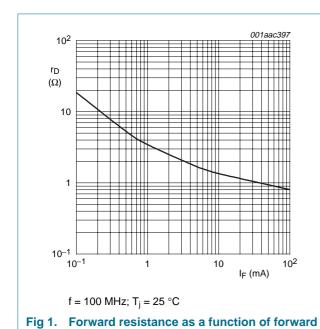
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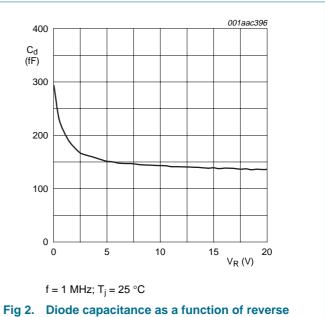
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 Table 6:
 Electrical characteristics ...continued

 $T_i = 25 \,^{\circ}C$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$ s_{21} ^2$	insertion loss	$I_F = 0.5 \text{ mA}$ ; see Figure 3				
		f = 900 MHz	-	0.4	-	dB
		f = 1800 MHz	-	0.39	-	dB
		f = 2450 MHz	-	0.4	-	dB
s <sub>21</sub>   <sup>2</sup>	insertion loss	I <sub>F</sub> = 1 mA; see Figure 3				
		f = 900 MHz	-	0.26	-	dB
		f = 1800 MHz	-	0.26	-	dB
		f = 2450 MHz	-	0.27	-	dB
s <sub>21</sub>   <sup>2</sup>	insertion loss	$I_F = 10 \text{ mA}$ ; see Figure 3				
		f = 900 MHz	-	0.11	-	dB
		f = 1800 MHz	-	0.11	-	dB
		f = 2450 MHz	-	0.12	-	dB
s <sub>21</sub>   <sup>2</sup>	insertion loss	I <sub>F</sub> = 100 mA; see Figure 3				
		f = 900 MHz	-	0.07	-	dB
		f = 1800 MHz	-	0.07	-	dB
		f = 2450 MHz	-	0.09	-	dB
τ∟	charge carrier life time	when switched from $I_F$ = 10 mA to $I_R$ = 6 mA; $R_L$ = 100 $\Omega$ ; measured at $I_R$ = 3 mA	-	0.55	-	μs
L <sub>S</sub>	series inductance	$I_F = 100 \text{ mA}; f = 100 \text{ MHz}$	-	0.6	-	nΗ

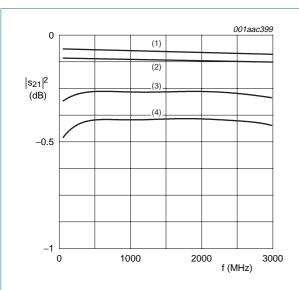




voltage; typical values

current; typical values

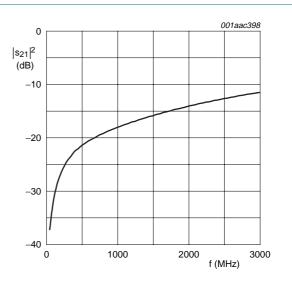
Silicon PIN diode



- (1)  $I_F = 100 \text{ mA}$
- (2)  $I_F = 10 \text{ mA}$
- (3)  $I_F = 1 \text{ mA}$
- (4)  $I_F = 0.5 \text{ mA}$

Diode inserted in series with a 50  $\Omega$  stripline circuit and biased via the analyzer Tee network

Fig 3. Insertion loss ( $|s_{21}|^2$ ) of the diode as a function of frequency; typical values



 $T_{amb} = 25 \, ^{\circ}C$ 

Diode zero biased and inserted in series with a 50  $\Omega$  stripline circuit

Fig 4. Isolation ( $|s_{21}|^2$ ) of the diode as a function of frequency; typical values

### **Package outline**

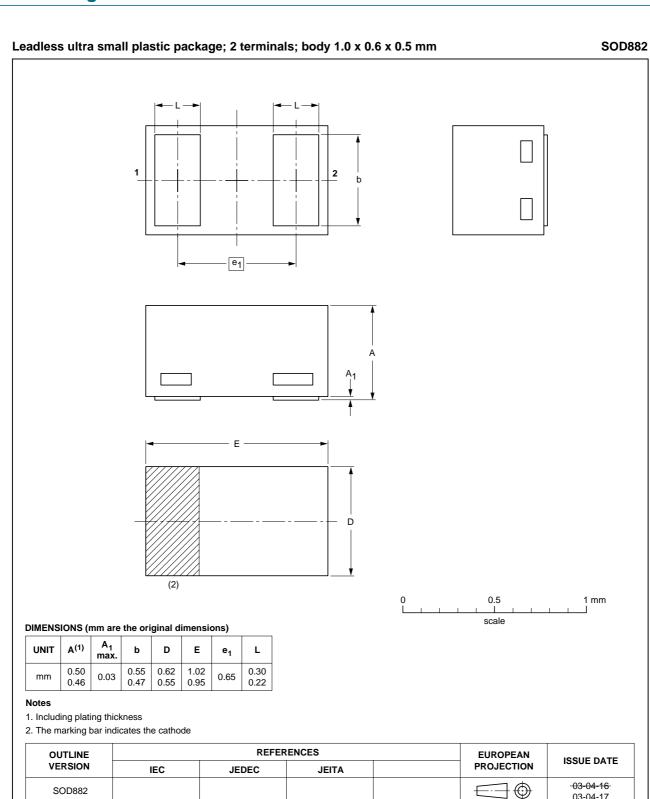


Fig 5. Package outline SOD882

SOD882

03-04-17





# 9. Revision history

### Table 7: Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
BAP51L_1	20050311	Product data sheet	-	9397 750 14554	-



### 10. Data sheet status

Level	Data sheet status [1]	Product status [2] [3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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